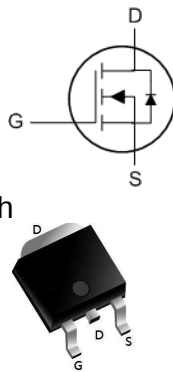


Description

The 30N10 is the high cell density trench N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The 30N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

100% EAS Guaranteed
Green Device Available
Super Low Gate Charge
Excellent CdV/dt effect decline
Advanced high cell density Trench technology

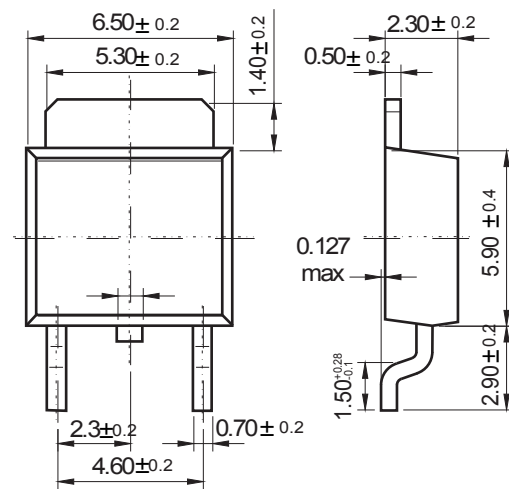


Product Summary

BVDSS	RDSON	ID
100V	37mΩ	27 A

TO-252

Unit: mm



Dimensions in inches and (millimeters)

Absolute Maximum Ratings (Tc=25°C unless otherwise specified)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		100	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Continuous Drain Current	T _C = 25 °C	27	A
		T _C = 100 °C	13	A
I _{DM}	Pulsed Drain Current ^{note1}		80	A
EAS	Single Pulsed Avalanche Energy ^{note2}		30	mJ
P _D	Power Dissipation	T _C = 25 °C	42	W
R _{θJC}	Thermal Resistance, Junction to Case		3.6	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C

30N10

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.2	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =10A	-	37	48	mΩ
		V _{GS} =4.5V, I _D =6A	-	39	55	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	1964	-	pF
C _{oss}	Output Capacitance		-	90	-	pF
C _{rss}	Reverse Transfer Capacitance		-	74	-	pF
Q _g	Total Gate Charge	V _{DS} =80V, I _D =20A, V _{GS} =4.5V	-	20	-	nC
Q _{gs}	Gate-Source Charge		-	3.1	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	14	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =80V, I _D =20A, R _G =3.1Ω, V _{GS} =4.5V	-	11	-	ns
t _r	Turn-on Rise Time		-	91	-	ns
t _{d(off)}	Turn-off Delay Time		-	40	-	ns
t _f	Turn-off Fall Time		-	71	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	27	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	80	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =20A	-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, dI/dt=100A/μs	-	64	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	152	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : T_J=25°C, V_{DD}=50V, V_G=10V, L=0.5mH, R_G=25Ω, I_{AS}= 11A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

RATING AND CHARACTERISTIC CURVES (30N10)

Figure1: Output Characteristics

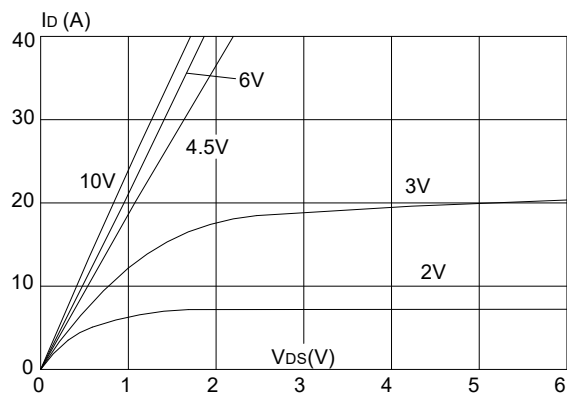


Figure 2: Typical Transfer Characteristics

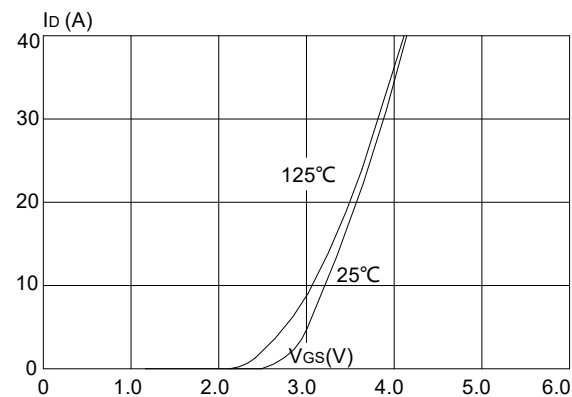


Figure 3: On-resistance vs. Drain Current

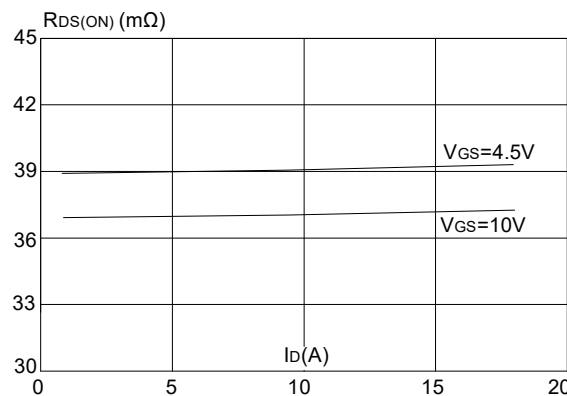


Figure 4: Body Diode Characteristics

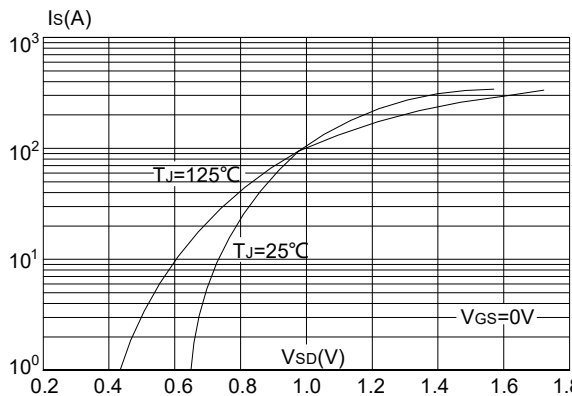


Figure 5: Gate Charge Characteristics

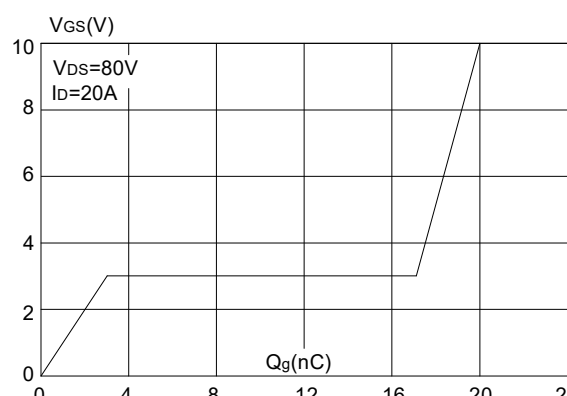
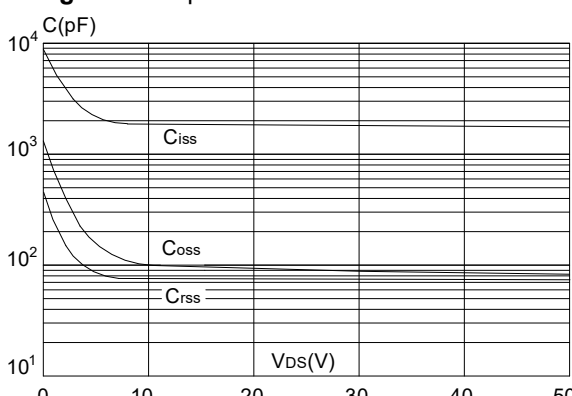


Figure 6: Capacitance Characteristics



RATING AND CHARACTERISTIC CURVES (30N10)

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

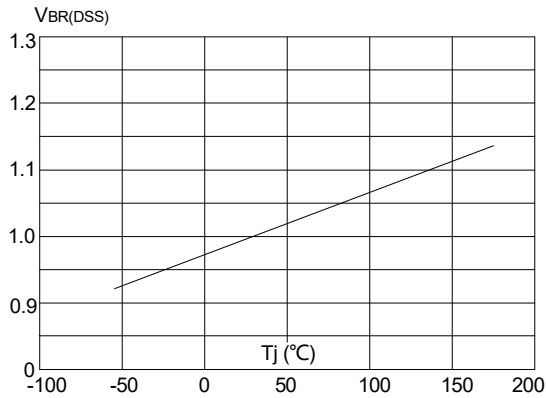


Figure 8: Normalized on Resistance vs. Junction Temperature

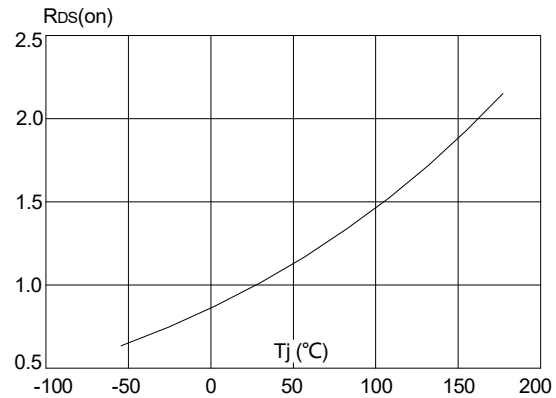


Figure 9: Maximum Safe Operating Area

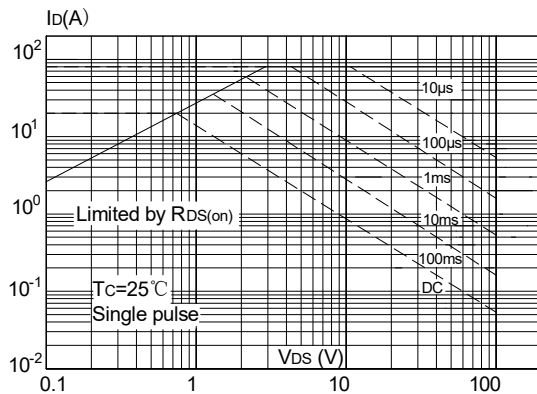


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

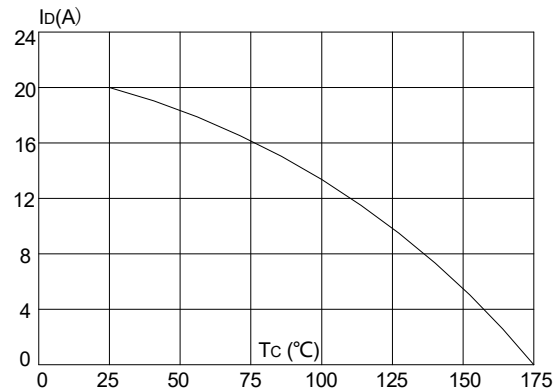


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

